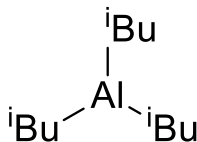


Catalog # 93-1358 Tri-*i*-butylaluminum, min. 95%

Thermal Behavior:

- Melting point: 4°C
- Boiling point: 73°C/5 Torr
- Decomposition: >200°C [2]
- Vapor pressure: 0.075 Torr/35°C; 1.5 Torr/45°C [3]; diagram is available in [2]

Technical Notes:

1. Precursor for aluminum containing thin film deposition.

Target Deposit	Deposition Technique	Delivery Temperature	Pressure	Co-reactants	Deposition Temperature	Ref.
Al	CVD	45°C	1 Torr	-	300-400°C	1
	CVD	82°C	-	-	225-500°C	2
		-	AP	-	275-317°C	3
AlN	ALD	86°C	1.7 Torr	N ₂ H ₄ ·HCl	200-350°C	4

References:

1. [Thin Solid Films 1998, 332, 312.](#)
2. [Powder Technol. 2006, 162, 100.](#)
3. [Chem. Vap. Deposition 2010, 16, 231.](#)
4. [Coatings 2020, 10, 954.](#)